

SPECIFICATION

REFOND P/N

RF-A1E30-W57H-B8

Mass Production



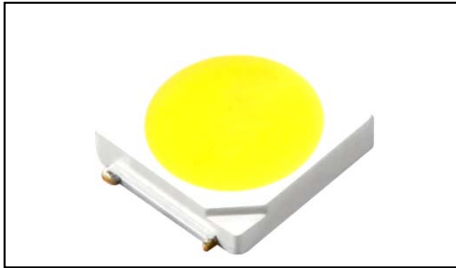
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4.1 Handling Precautions	



1. Description

1.1 General Description



The White LED, which was fabricated by using a blue chip and the phosphor.

Product Package:3.2mmX3.0mmX0.6mm.

3.2mmX3.0mmX0.6mm

1.2 Features

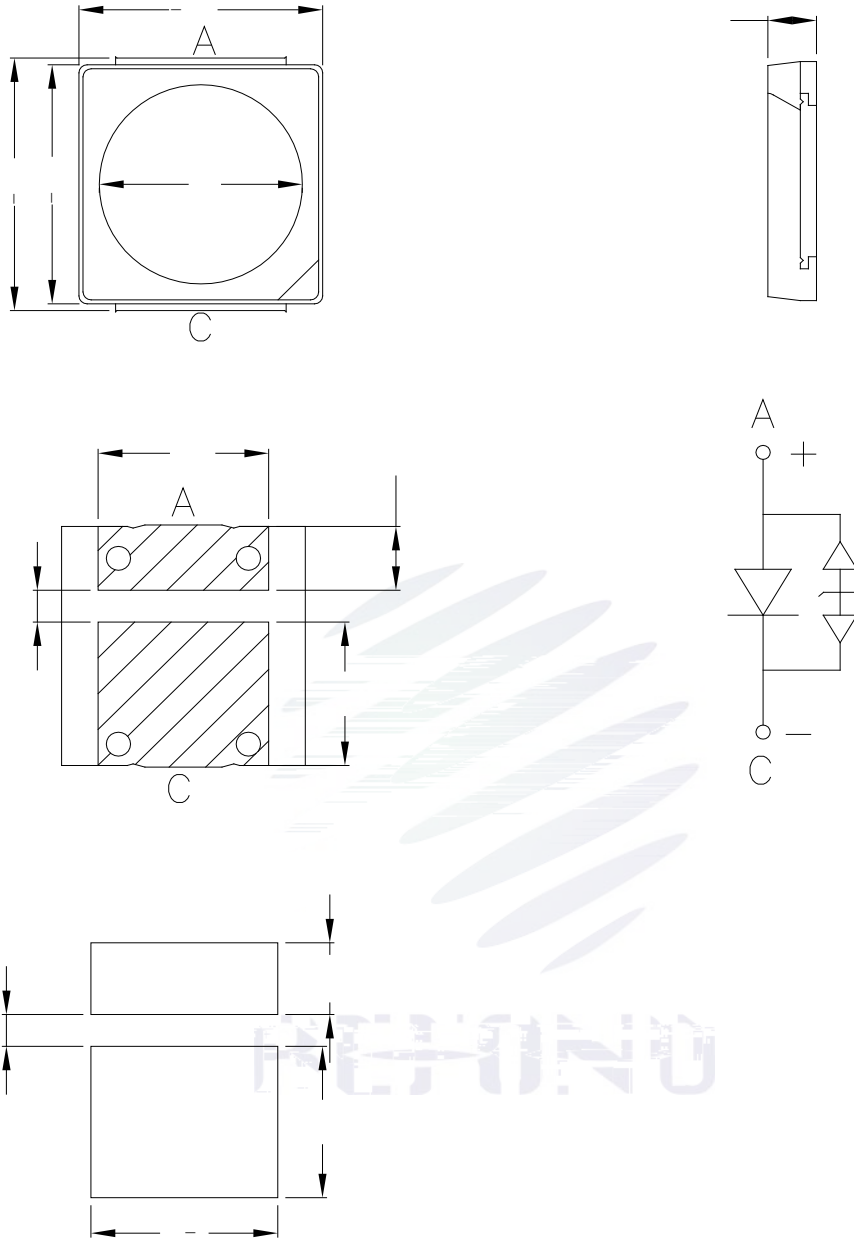
- ▶ EMC Package.EMC
- ▶ Extremely wide viewing angle.
- ▶ Suitable for all SMT assembly and solder process. SMT
- ▶ Available on tape and reel.
- ▶ Moisture sensitivity level: Level 2. Level2
- ▶ Compliance with RoHS and REACH.
- ▶ Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101 Stress Test Qualification for Automotive Grade Discrete Semiconductors -Q101

1.3 Application

- ▶ Automotive Exterior Lighting.



1.4 Package Dimension



Notes

1. All dimensions units are millimeters.
2. All dimensions tolerances are 0.2mm unless otherwise noted.



1.5 Product Parameters

Table 1-1 Electrical / Optical Characteristics at Ts=25°C

Item	Symbol	Test Condition	Value			Unit
			Min.	Typ.	Max.	
Forward Voltage	V_F	$I_F=350\text{mA}$	2.8	---	3.4	V
Reverse Current	I_R	$V_R=5\text{V}$	---	---		μA
Luminous Flux	Φ	$I_F=350\text{mA}$	117	137	160	lm
Viewing Angle	2 θ 1/2	$I_F=350\text{mA}$	---	120	---	d

Table 1-2 Absolute Maximum Ratings at Ts=25°C



Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate
8. ESD yield is over 90% at 8000V ESD (HBM). ESD protection during products handling is needed.

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1.6 Bin Range Of Forward Voltage and Luminous Flux (IF=350mA)

BIN (IF=350mA)

Table 1-3

V _F	G1	G2	H1	H2	I1	I2		
	2.8-2.9	2.9-3.0	3.0-3.1	3.1-3.2	3.2-3.3	3.3-3.4		
φ	SB	TA	TB					
	117-130	130-144	144-160					



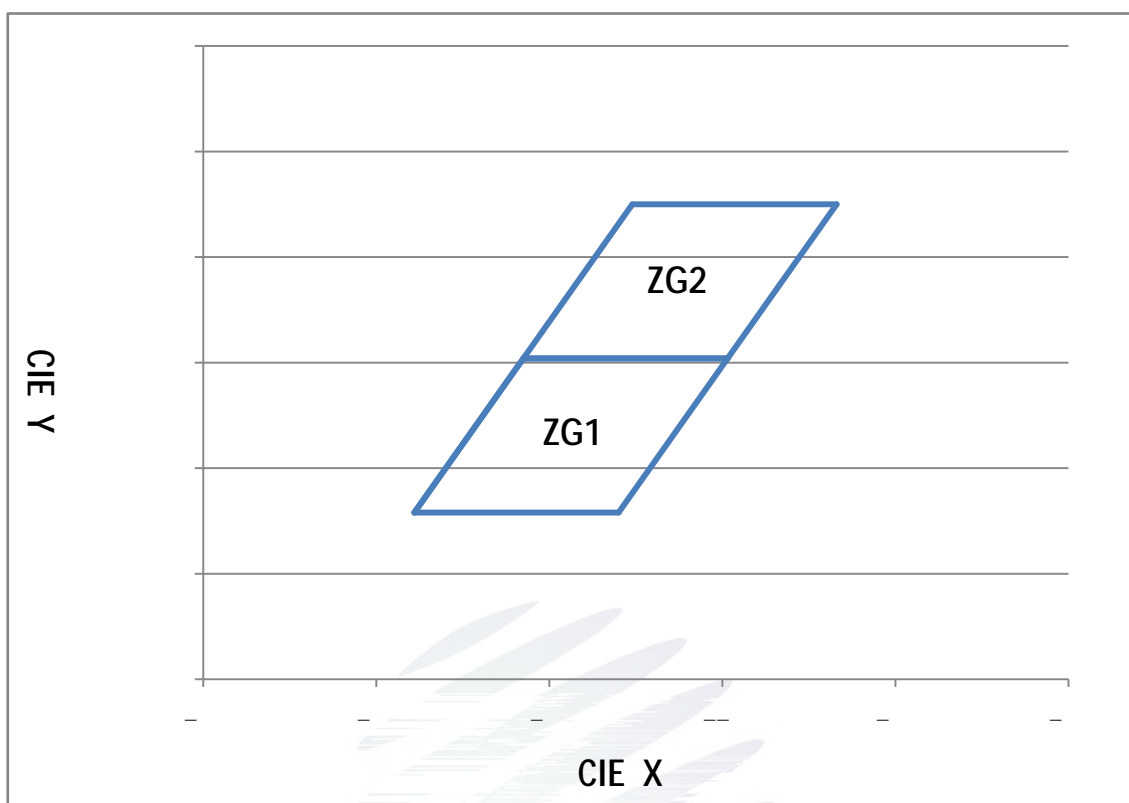


Fig. 1-6 The C.I.E Chromaticity Diagram CIE

Table 1-4

BIN CODE	CIE-X1	CIE-Y1	CIE-X2	CIE-Y2	CIE-X3	CIE-Y3	CIE-X4	CIE-Y4
ZG1	0.3122	0.3258	0.3185	0.3404	0.3303	0.3404	0.324	0.3258
ZG2	0.3185	0.3404	0.3248	0.355	0.3366	0.355	0.3303	0.3404



1.7 Typical Optical Characteristics Curves

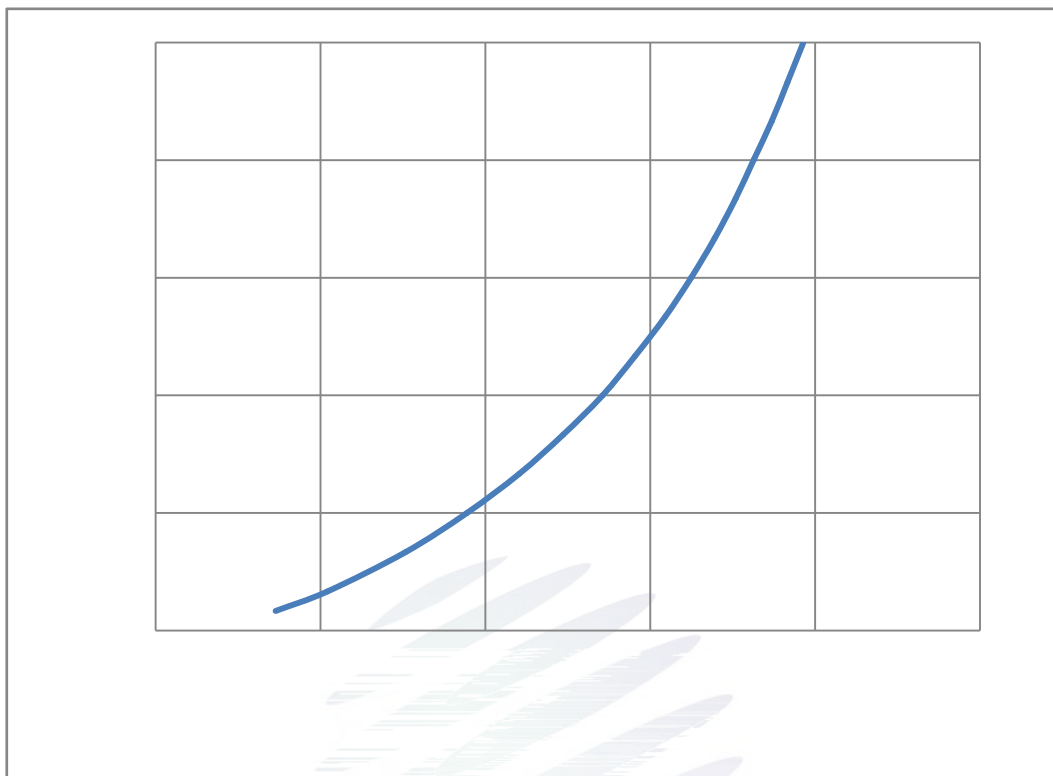


Fig. 1-7 Forward Voltage Vs Forward Current

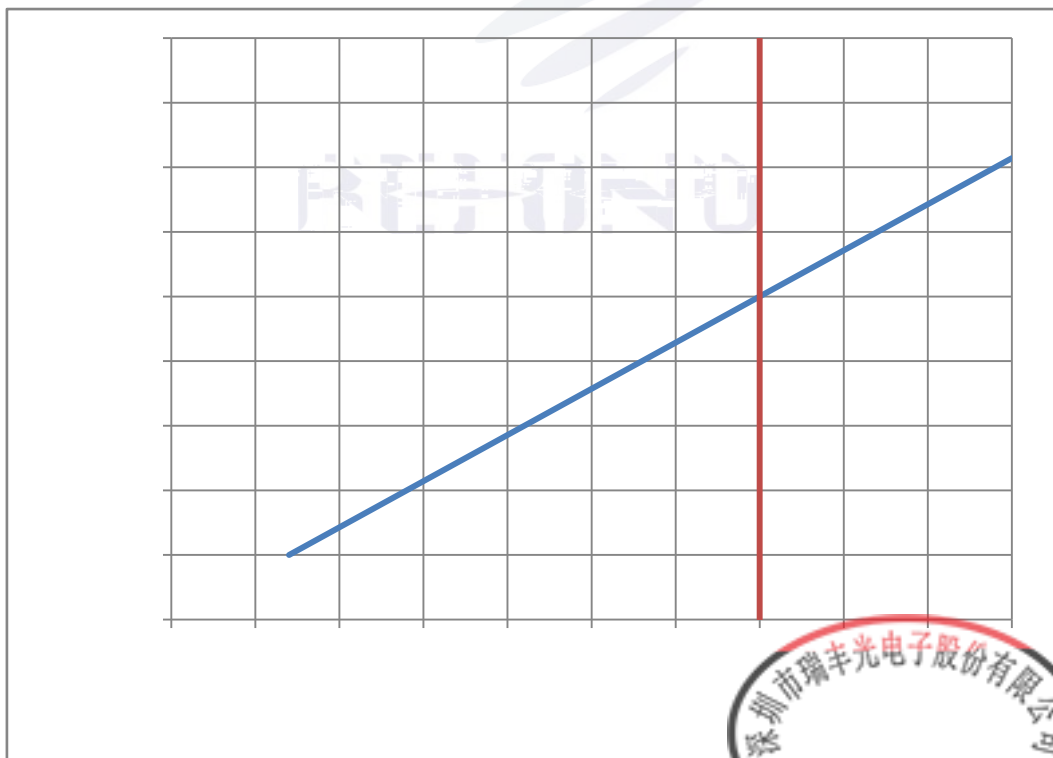


Fig. 1-8 Forward Current Vs Relative Intensity



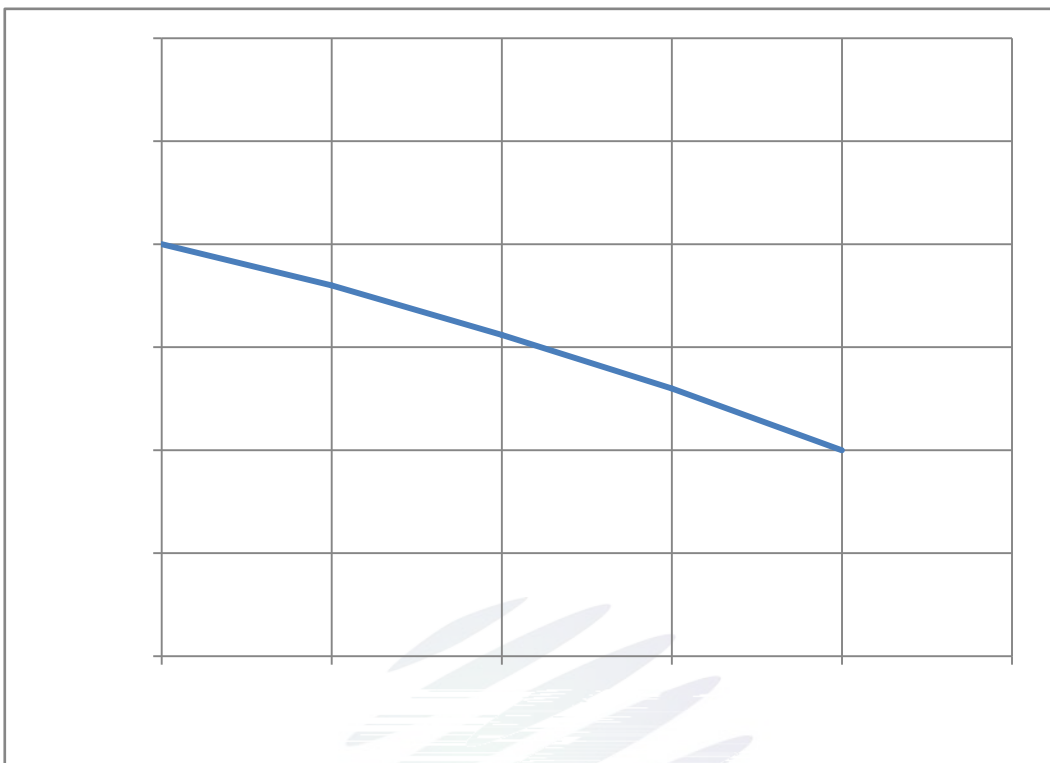


Fig. 1-9 Solder Temperature Vs Relative Intensity

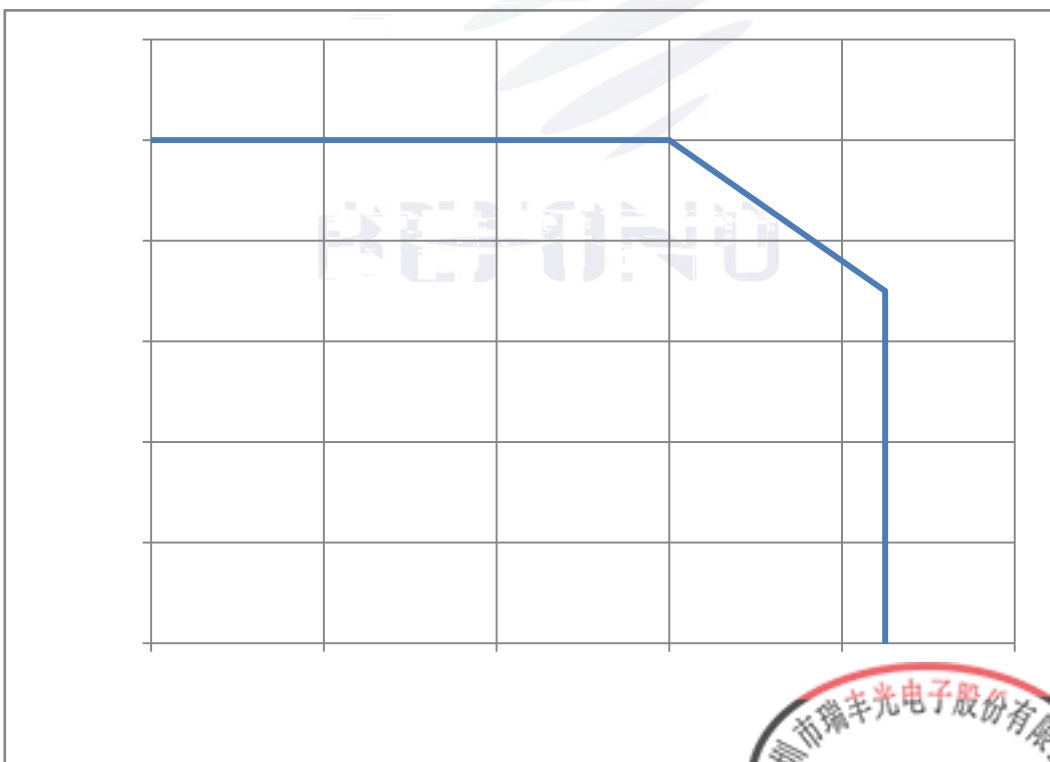


Fig. 1-10 Solder Temperature Vs Forward Current



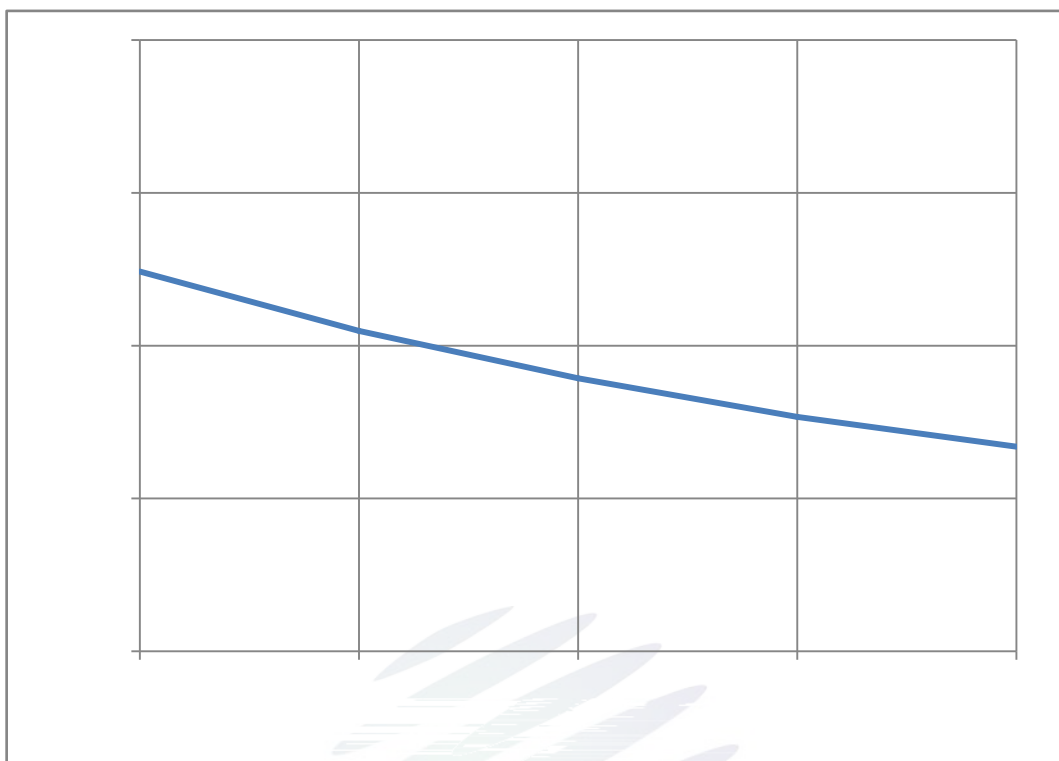


Fig. 1-11 Forward Voltage Vs Solder Temperature

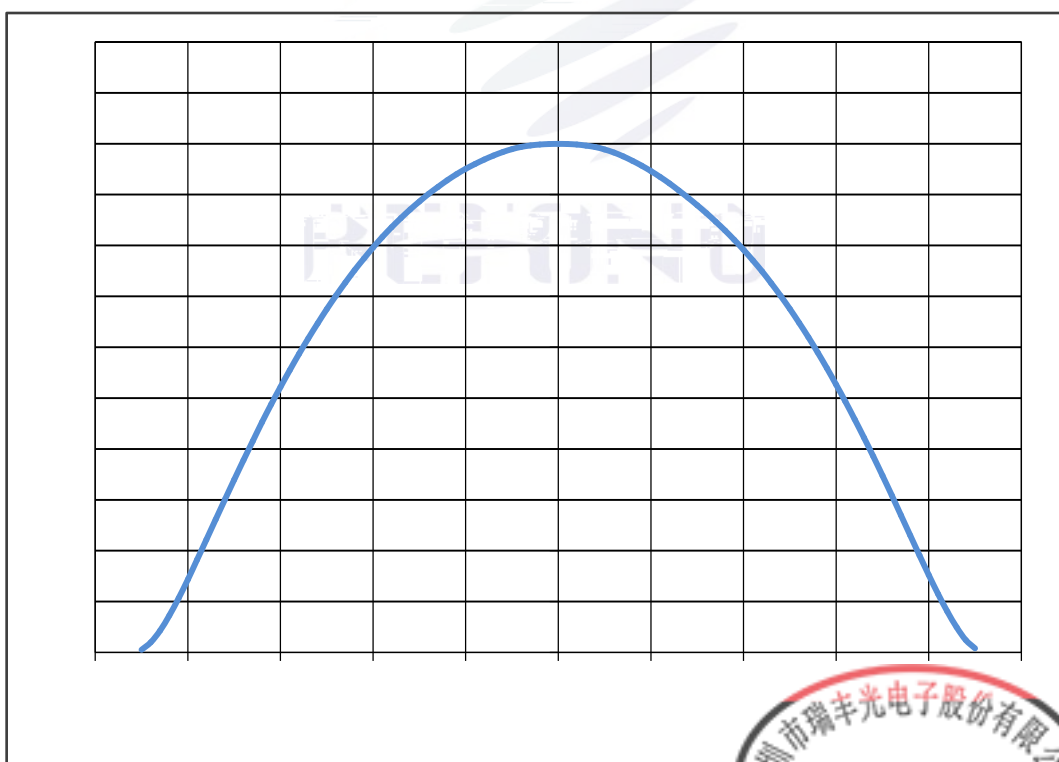


Fig. 1-12 Radiation diagram



Fig. 1-13 Chromaticity Coordinate Shift Vs Forward Current



Fig. 1-14 Spectrum Distribution

2. Packaging

2.1 Packaging Specification

Package:4000pcs/reel.

2.1.1 Carrier Tape Dimension

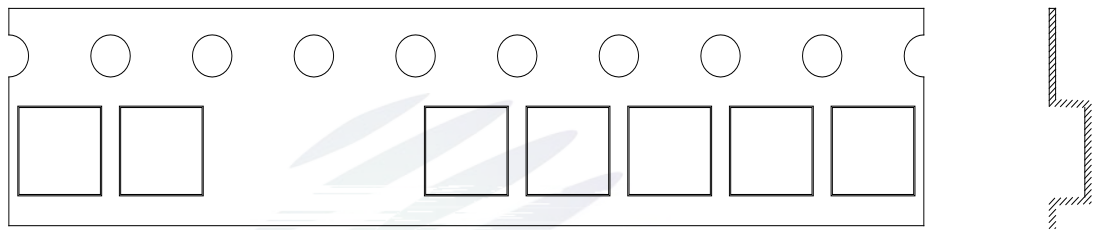


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

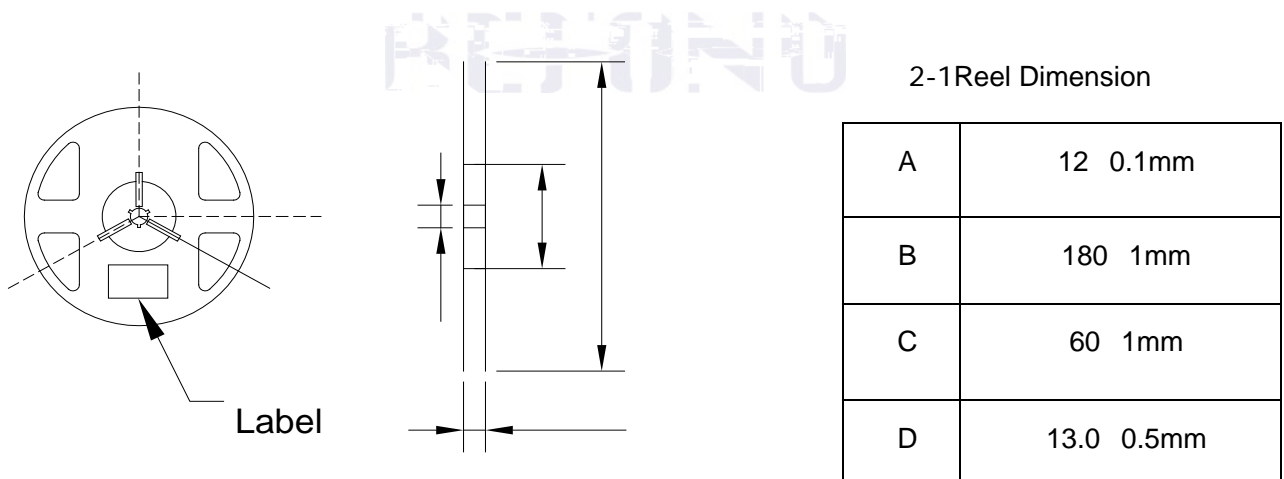


Fig.2-2 Reel Dimension

Notes

The tolerances unless mentioned $\pm 0.1\text{mm}$. Unit : mm

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2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re
Reflow	JESD22-B106 JEDEC-88.02	Temp:260 max T ₂ T _c 0.002 T=10 sec	25min	0.90±0.03	0.01 <0.783/(T _f -0.00



2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V_F	$I_F=350\text{mA}$	-	U.S.L*)x1.1
Reverse Current	I_R	$V_R = 5\text{V}$	-	U.S.L*)x2.0
Luminous Flux	Φ	$I_F=350\text{mA}$	L.S.L*)x0.7	-

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others. /
- 3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



3. SMT Reflow Soldering Instructions SMT

3.1 SMT Reflow Soldering Instructions SMT

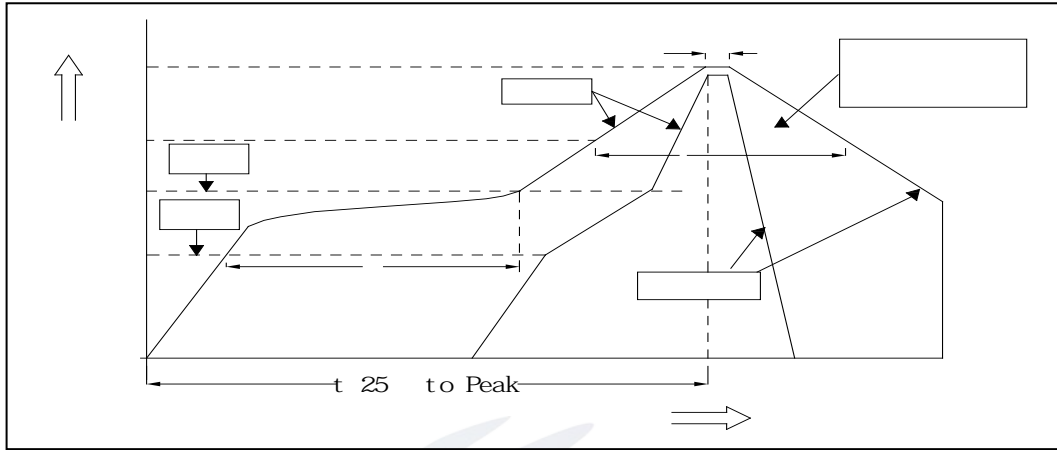


Fig.3-1 SMT Reflow Soldering Instructions SMT

Table 3-1 Reflow parameters

Average temperature rise speed	T_{smax} T_P	3 °C/ Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})	150 °C
Preheating: Max temperature	(T_{smax})	200 °C
Preheating: Time	T_{smin} T_{smax}	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature	(T_L)	217 °C
Time limited to maintain high temperature: The Time	(t_L)	60 Max 60s
Peak /Classification of temperature:	/ (T_P)	260 °C
Time limit classification of peak temperature time	t_p	10 Max 10s
(T_P) 5 °C Hold time within		30 Max 30s
5 °C with the actual peak temperature (T_P)		
Cooling speed		6 °C/ Max 6 °C/ s
25 °C	Needed time from 25 °C to T_P	8 Max 8 minutes



Notes

(1)Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings ,LED will be damaged. 24

(2)When soldering , do not put stress on the LEDs during heating.

3.1.1 Repairing

Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable,a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

LED

3.1.2 Cautions

(1) The encapsulated material of the LEDs is silicone. Therefore the LEDs have a soft surface on the top of package. The pressure to the top surface will be impacted on the reliability of the LEDs. Precautions should be taken to avoid the strong pressure on the encapsulated part. So when use the picking up nozzle, the pressure on the silicone resin should be proper. LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board.LED PCB

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.



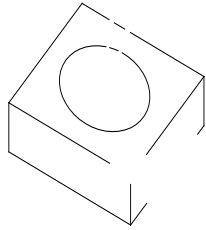


Fig 4-1Cautions

(5) In designing a circuit, the current through each LED can not exceed the absolute maximum rating specified for each LED. In the mean while, resistors for protection should be applied, other wise slight voltage shift will cause big current change, burn out may happen. The driving circuit must be designed to allow forward voltage only when it is ON or OFF. If the reverse voltage is applied to LED, migration can be generated resulting in LED damage.

(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.



j E.5

